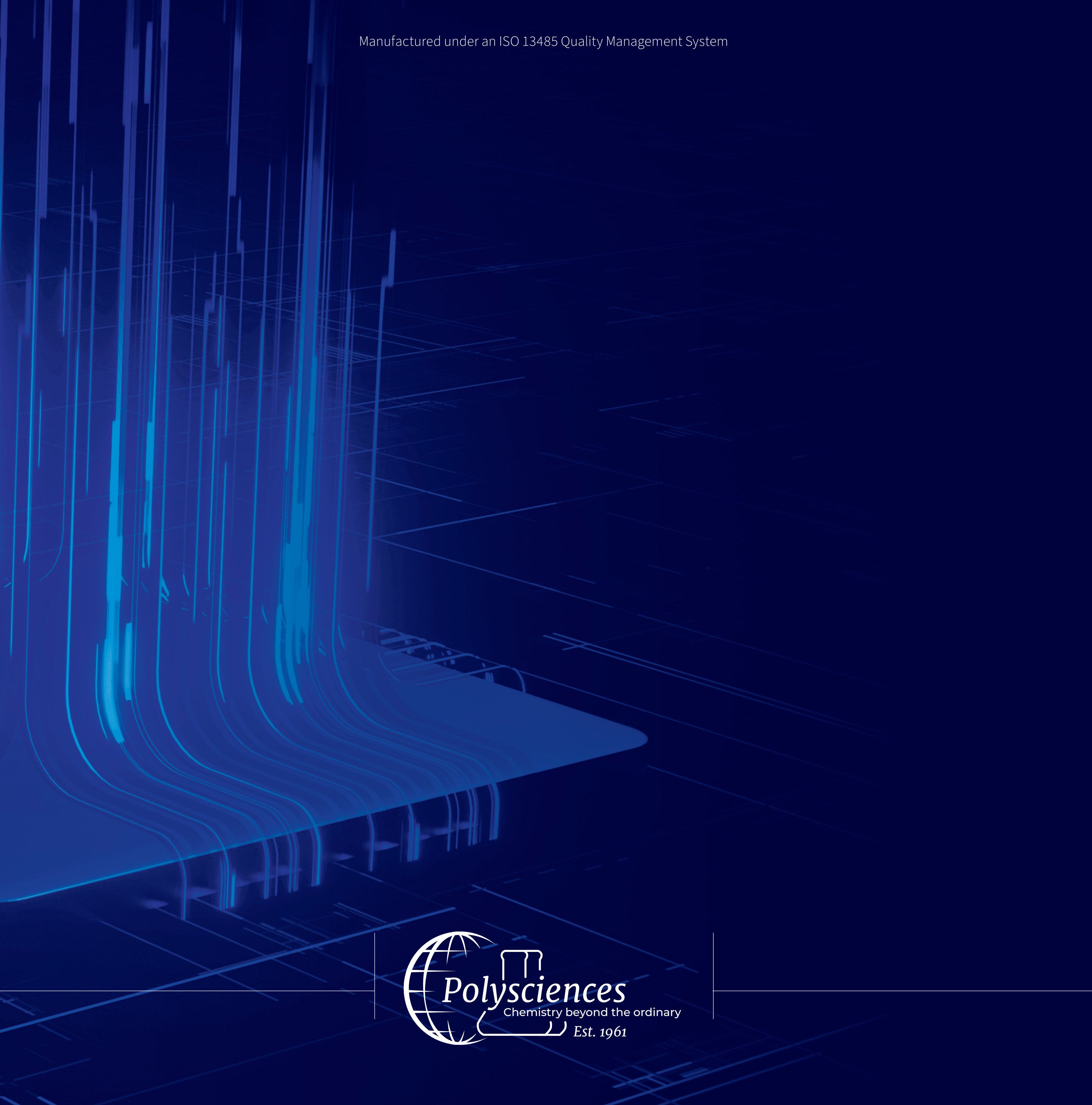
ELECTRONIC CHEMICALS

High performance adhesives, coatings, & encapusulants

Manufactured under an ISO 13485 Quality Management System



Polysciences
Chemistry beyond the ordinary
Est. 1961

As electronics manufacturing expands, Polysciences is positioned to be your material supplier of choice. Our electronic chemical division offers an expanded line of electronics polymers and chemicals that includes underfills, liquid encapsulants, die attach and optical adhesives for advanced applications. Additionally, we can provide custom formulation, high purity polymer and monomer synthesis, as well as contract packaging services to meet your specifications. We are steadfast in our commitment to provide exceptional products and services through our scientific expertise, state-of-the-art facilities and quality systems, now and into the future.

Our standard electronics chemical products consist of:

- Semiconductor Adhesives
- Encapsulants & Dams
- Coatings, WLP
- Optical Encapsulants
- Potting Compounds
- CMP Chemicals (Chemical Mechanical Polishing) for wafer polishing
- Particle Size Standards for wafer calibration machines, clean room certification & filter certification

ADHESIVES, COATINGS & ENCAPSULANT PRODUCT HIGHLIGHTS

LoSTRESS™ Liquid Encapsulants & dams

Very low stress encapsulant for fragile substrates, e.g.

Cat#	Product Description
SF54GB	SF54GB LoSTRESS™ Liquid Encapsulant *(Thermal Epoxy)*
PC7010	PC7010 UV Curable Encapsulant & Adhesive *(UV Acrylate)*
SF54HV	LoSTRESS™ SF54HV Liquid Encapsulant *(Thermal Epoxy)*
SF5021	SF5021 OptiCLEAR™ Liquid Encapsulant Fill *(UV Epoxy)*

OptiCLEAR™ Optical Adhesive

Enhances UV and thermally curable process, e.g.

Cat#	Product Description
SF503A	SF503A OptiCLEAR™ Liquid Encapsulant Fill *(UV Epoxy)*
SF1012	OptiCLEAR™ SF1012 *(UV Epoxy)*
SF5021	SF5021 OptiCLEAR™ Liquid Encapsulant Fill *(UV Epoxy)*
SF850K	SF850 A&B OptiCLEAR™ Liquid Encapsulant Fill *(2-part Thermal Epoxy)*

NoSWEEP™ Wire Bond Encapsulants

Eliminates wire sweep, sway and sag, e.g.

Cat#	Product Description
UC5001	UC5001 EasyFILL™ *(Thermal Epoxy)*
EW8002	EW8002 NoSWEEP™ Wire Bond Encapsulant *(Thermal Epoxy)*

General Potting & Encapsulation Materials

Epoxy or Silicone

Thermally Conductive or Electrically Conductive

One part and 2 part systems, e.g.

Cat#	Product Description
PC8007	PC8007 Low Viscosity Glob Top Encapsulant *(Thermal Epoxy)*

Edgefill / Dam Encapsulants

High viscosity, low creep, e.g.

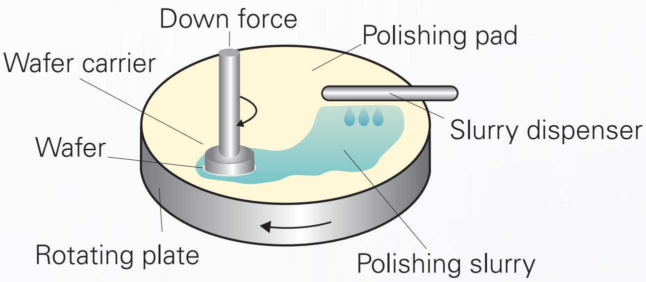
Cat#	Product Description
SD1011	SD1011 EdgeCONTROL™ *(Thermal Epoxy)*

Underfill

Cat#	Product Description
UC5001	UC5001 EasyFILL™ *(Thermal Epoxy)*

POLYMERS FOR CHEMICAL MECHANICAL POLISHING

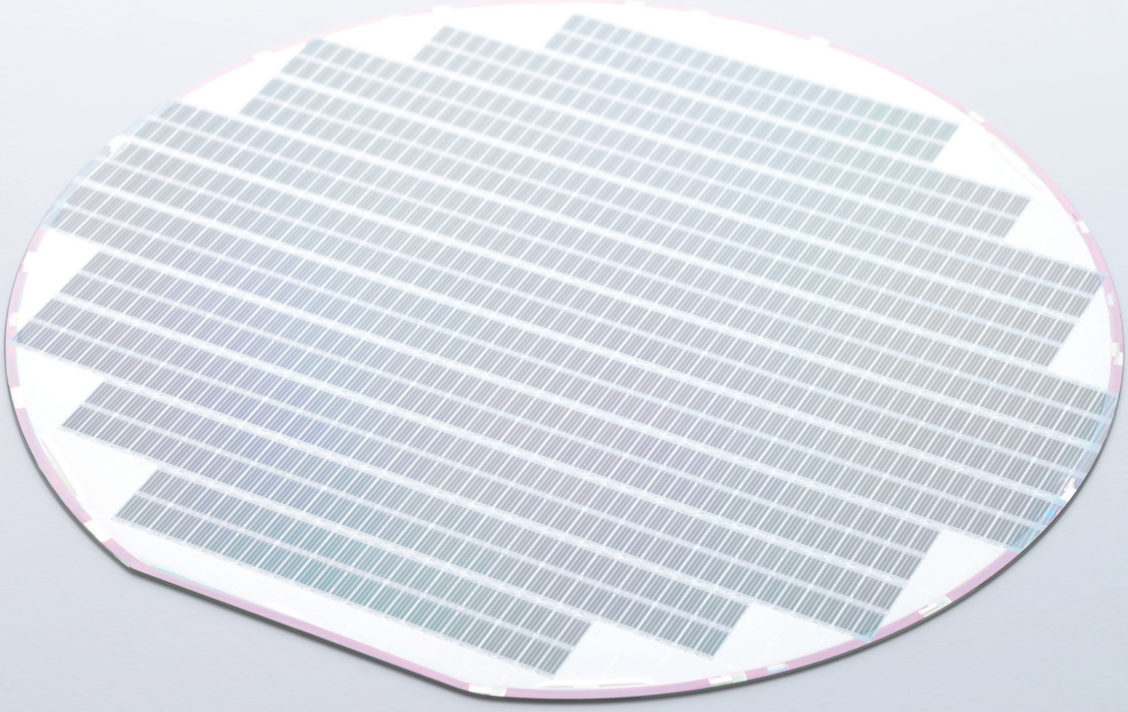
During the processing of silicon wafers as semiconductors, a critical step is the flattening and levelling of the wafer. Chemical Mechanical Polishing, or CMP, is the process to produce an extremely flat, level and smooth wafer surface. Because of its good pigment dispersion properties, Poly(Acrylic Acid), PAA, is a potential liquid media for making such slurries. To provide specialized grades of PAA suitable for use in electronics industry CMP slurry materials, Polysciences has developed manufacturing processes that yield highly purified PAA. Our proprietary methods produce low ionic content, low particulate content, stringently purified PAA that is highly useful as a CMP slurry dispersant.

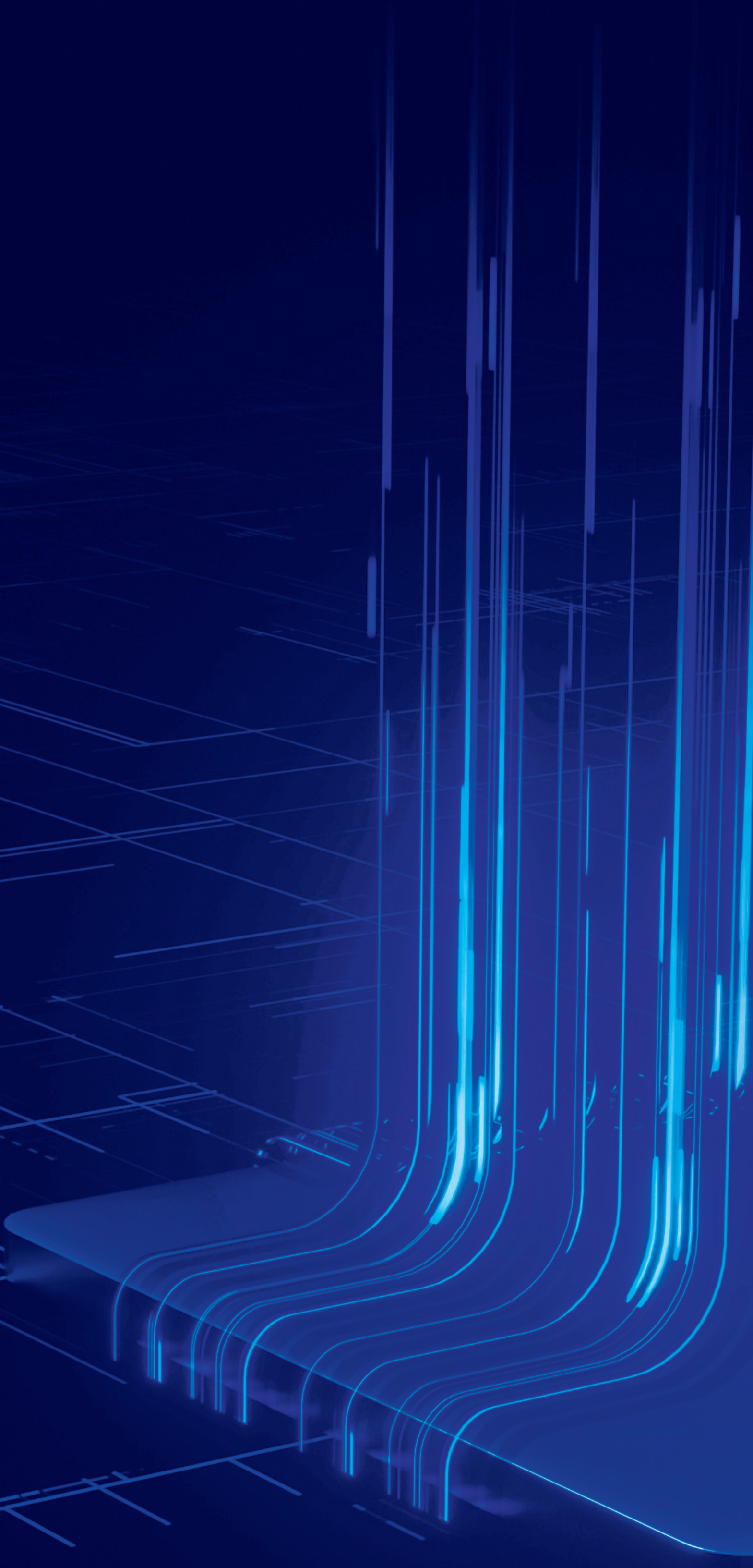


We are pleased to offer our scientific and technical expertise, strong ISO 13485:2016 Quality Management System and cGMP capabilities to our partners in the electronics industry. Please reach out to us to find out how we can put our decades of knowledge and real-world experience to work for you.

POLY(ACRYLIC ACID) & PEI PRODUCT HIGHLIGHTS

Cat#	Product Description
14433	Poly(Acrylic Acid) Ultrapure Mw 2,000
12864	Poly(Acrylic Acid) UltrapureMw 5,000
13511	Poly(Acrylic Acid) Ultrapure Mw 10,000
13449	Poly(Acrylic Acid) Ultrapure Mw 30,000
14205	Poly(Acrylic Acid) Ultrapure Mw 50,000
13150	Poly(Acrylic Acid) Ultrapure Mw 340,000
13620	Poly(Acrylic Acid) Ultrapure Mw 1,000,000
12715	Poly(ethylene imine) Ultrapure Mw 70,000





U.S. Corporate Headquarters
Polysciences
400 Valley Rd.
Warrington, PA 18976
1(800) 523-2575 / (215) 343-6484
1(800)343-3291 fax
info@polysciences.com

GLOBAL SALES OFFICES

Europe Sales Office
Polysciences Europe GmbH
Badener Str. 13
69493 Hirschberg an der Bergstrasse, Germany
+(49) 06201-845 20 0
+(49) 06201-845 20 20 fax
info@polysciences.de

Asia Sales Office
Polysciences Asia-Pacific, Inc.
2F-1, 207 DunHua N. Rd.
Taipei, Taiwan 10595
(886) 2 8712 0600
(886) 2 8712 2677 fax
info@polysciences.tw

India Sales Office
Ott Scientific India Pvt. Ltd.
Plot no 805, 1st Floor
Udyog Vihar, Phase V
Gurugram, Haryana 122016 India
91 730 370 2008
info@ottscientific.in

Brazil Sales
Ott Scientific Brasil
Avenida Paulista, 1374, 11° andar, Sala 11A142
Bela Vista - São Paulo/SP
CEP 01310-916, Brasil
55 11 3164-0521
info@ottscientific.com.br